EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	218	((HIDEO) near2 (TANAKA)).INV.	US-PGPUB; USPAT	OR	OFF	2009/05/15 09:17
L9	122	349/51.ccls. and (scan scanning gate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 10:31
L10	4	349/51.ccls. and (gate adj bus)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 10:49
L11	5	349/40.ccls. and 349/51. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 10:52
L12	1	"5117299".PN.	USPAT; USOCR	OR	OFF	2009/05/15 10:55
L13	40	349/51.ccls. and (silicon adj nitride)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:11
L14	4319	"349"/\$.ccls. and gate near4 line with source with drain	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:23
L15	513	"349"/\$.ccls. and gate near4 line with (on top above) with source with drain	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:23
L16	513	"349"/\$.ccls. and (gate near4 line) with (on top above) with source with drain	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:24

L17	53	"349"/\$.ccls. and (gate adj bus adj line) with (on top above) with source with drain	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:40
L18	9	L17 and (MIM metal near2 insulator near2 metal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:40
L19	1361	"349"/\$.ccls. and (top near3 (gate scan scanning))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 11:44
L20	158	L19 and (MIM metal near2 insulator near2 metal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:44
L21	24	"6407791"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 11:58
L22	22	"5128784"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:07
L23	2	349/51.ccls. and inter near2 insulating near2 layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:08
L24	134	349/51.ccls. and insulat\$3 with substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:09

L25	331	349/51.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:10
L26	2	"5781256"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:11
L29	2	349/51.ccls. and (nanometer nm) with (gate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:23
L30	2	349/51.ccls. and (nanometer nm) with (gate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 12:23
L31	1055	"349"/\$.ccls. and (nanometer nm) with (gate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 12:23
L32	822	"349"/\$.ccls. and (nanometer nm) with (gate adj insulat\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 12:23
L33	790	"349"/\$.ccls. and (nanometer nm) with (gate adj insulat\$3) with (thin thinner thick thicker thickness)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 12:24
L34	734	"349"/\$.ccls. and (nanometer nm) with (gate adj insulat\$3) with (thickness)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 12:24

L36	168	L34 and (TFD MIM metal near2 insulat\$3 near2 metal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 12:25
L37	7	349/51.ccls. and mask with gate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/15 12:39
L41	6	"349"/\$.ccls. and exposure with large with contact adj hole	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:47
L42	0	"349"/\$.ccls. and contact adj hole with (uv irradiation) with (larger more large)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:49
L43	0	"349"/\$.ccls. and contact adj hole with (uv irradiation) with (larger more large longer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:49
L44	16	"349"/\$.ccls. and contact adj hole with (photolithography) with (larger more large longer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:49
L45	76	"349"/\$.ccls. and contact adj hole with (expos\$5) with (larger more large longer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 12:50
L46	640	"349"/\$.ccls. and (half diffraction) near5 mask	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 13:02

L47	28	"349"/\$.ccls. and (half	US-PGPUB;	OR	OFF	2009/05/15
		diffraction) near5 mask	USPAT;			13:02
		with (low lower small)	USOCR; FPRS;			
		with exposure	EPO; JPO;			
			DERWENT;			
	,,,,,,,,		IBM_TDB			

5/15/2009 1:06:35 PM

C:\ Documents and Settings\ Ichien\ My Documents\ EAST\ Workspaces\ 10596843.wsp